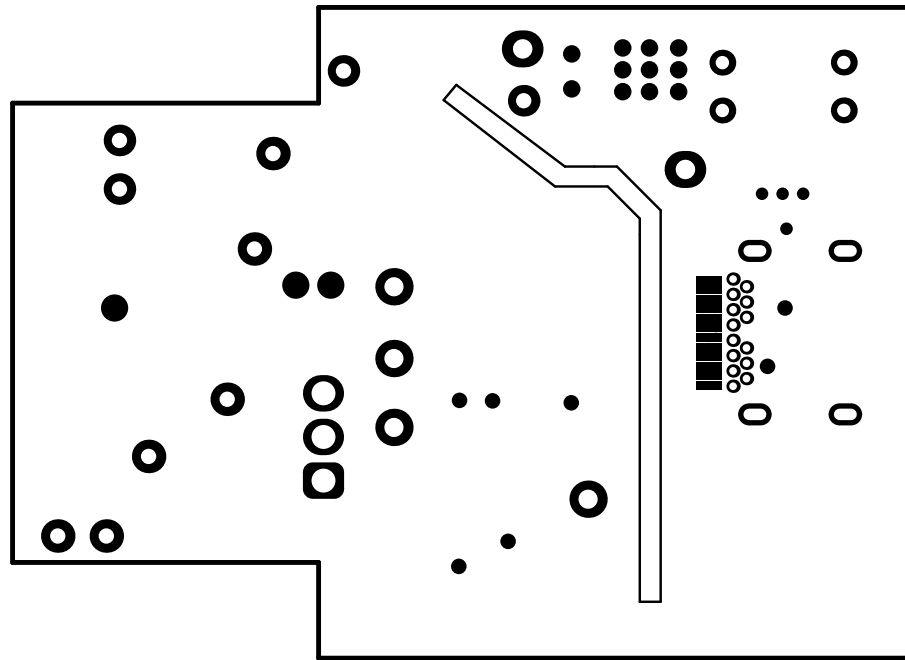
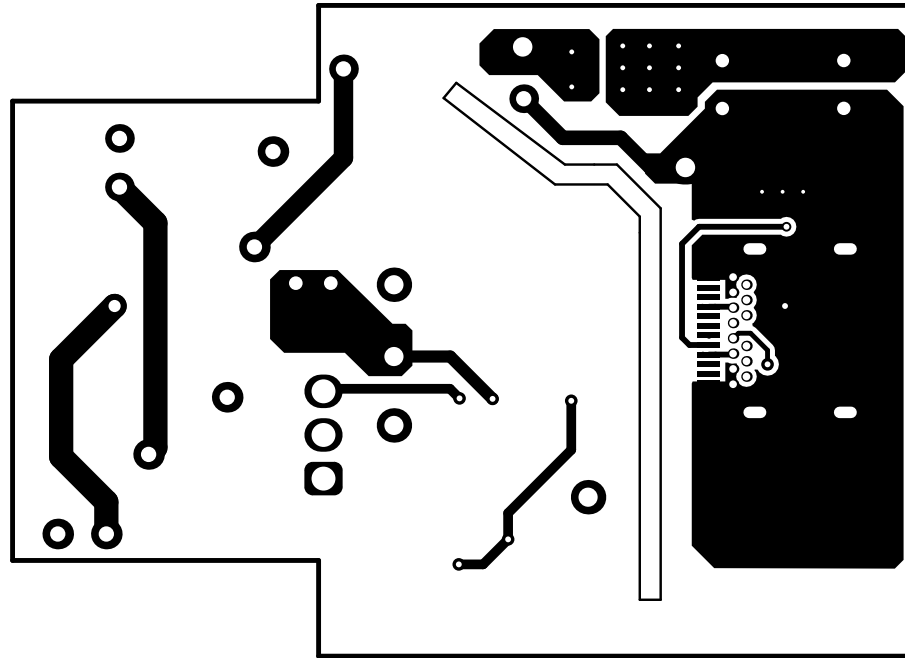


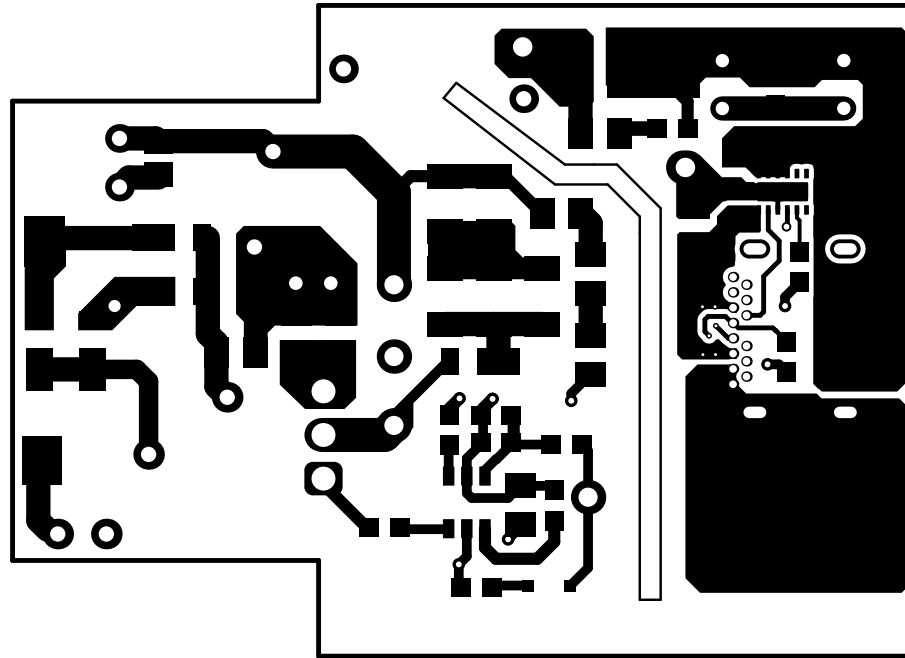
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40260	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: PMP40260		
PLOT NAME = Top Overlay	GENERATED : 11/8/2017	1:25:14 PM	TEXAS INSTRUMENTS



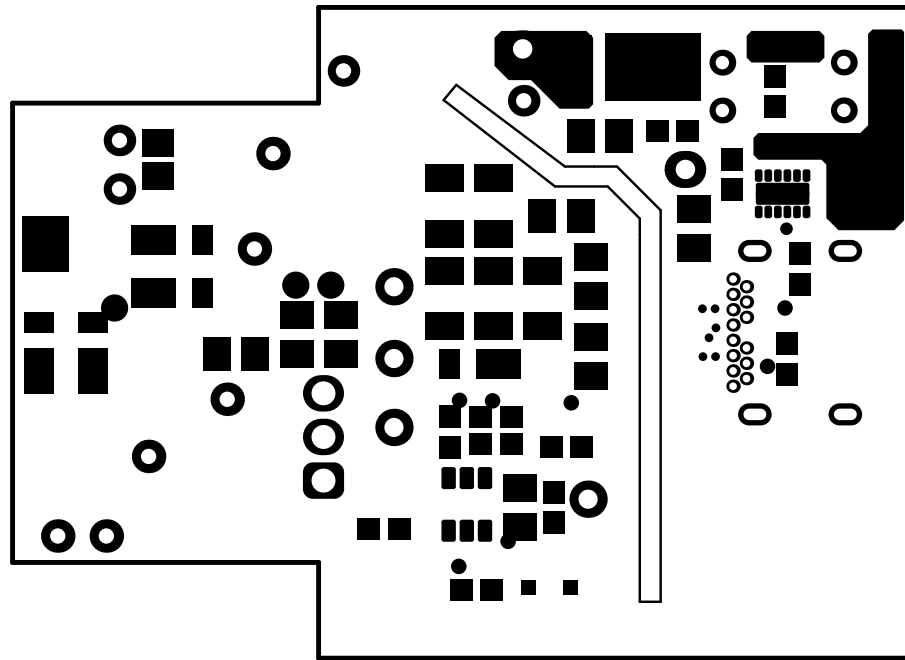
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40260	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: PMP40260		
PLOT NAME = Top Solder Mask	GENERATED : 11/8/2017	1:25:15 PM	TEXAS INSTRUMENTS



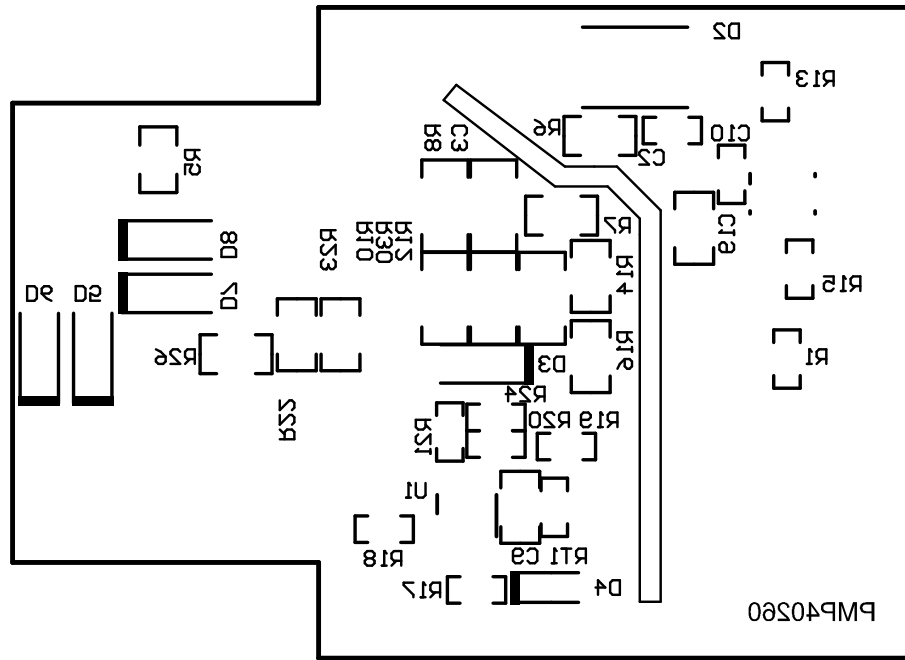
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40260	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP40260		
PLOT NAME = Top Layer	GENERATED : 11/8/2017	1:25:17 PM	TEXAS INSTRUMENTS



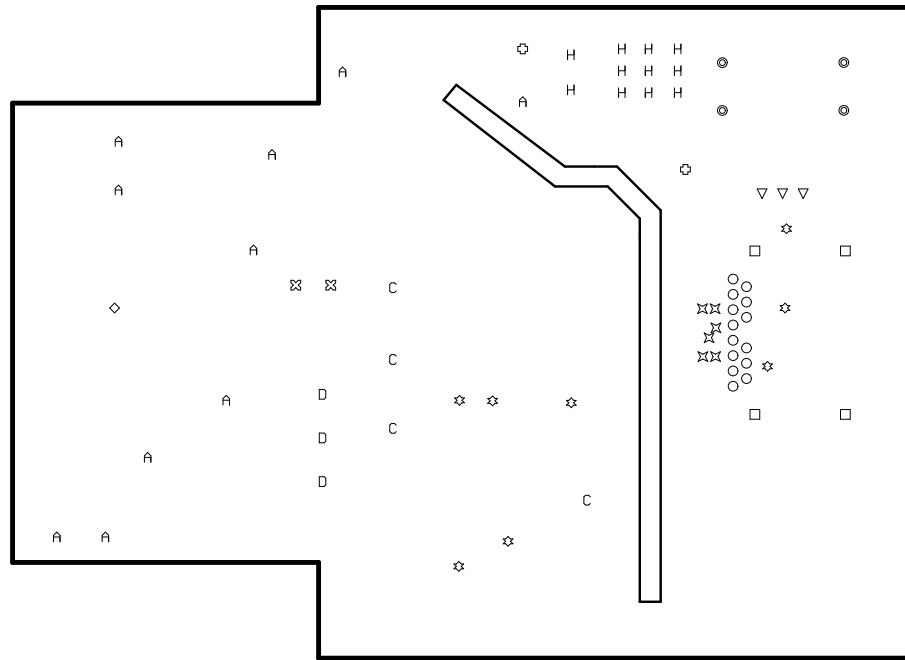
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40260	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP40260		
PLOT NAME = Bottom Layer	GENERATED : 11/8/2017	1:25:18 PM	TEXAS INSTRUMENTS



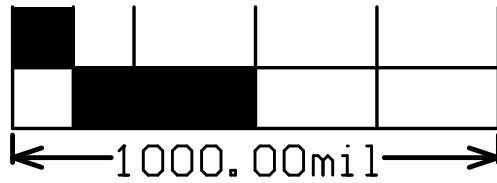
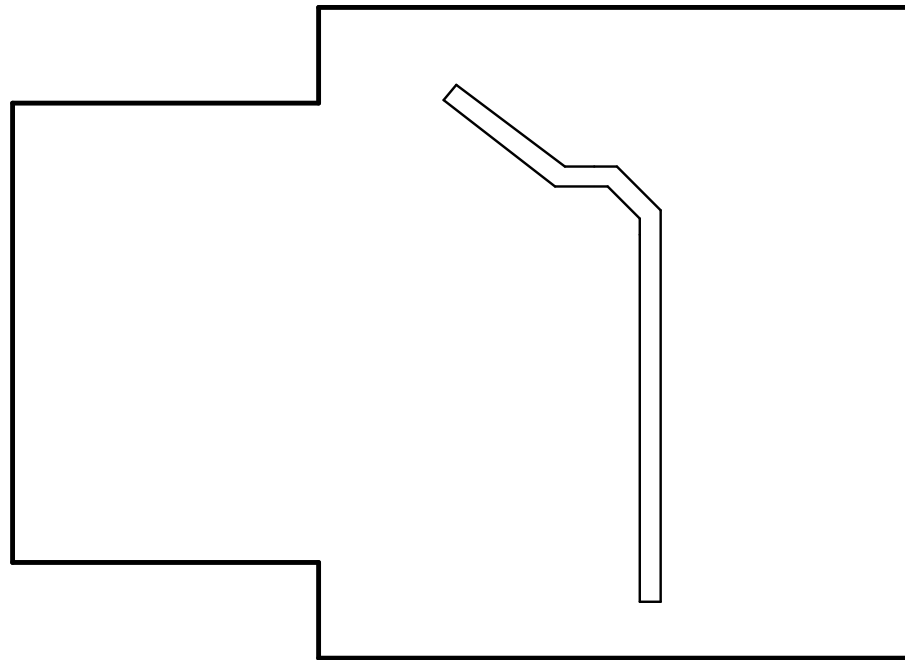
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40260	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP40260		
PLOT NAME = Bottom Solder Mask	GENERATED : 11/8/2017 1:25:19 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40260	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: PMP40260		
PLOT NAME = Bottom Overlay	GENERATED : 11/8/2017	1:25:21 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40260	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP40260		
PLOT NAME = Drill Drawing	GENERATED : 11/8/2017 1:25:22 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40260	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP40260		
PLOT NAME = Board Dimensions	GENERATED : 11/8/2017 1:25:24 PM	TEXAS INSTRUMENTS	

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